

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
SEQUENCE:	4
CONVEYING PARTY DATA	
Name	Execution Date
INTEGRATED CIRCUIT SOLUTION, INC.	08/18/2015
RECEIVING PARTY DATA	
Name:	CHINGIS TECHNOLOGY CORPORATION
Street Address:	3F, NO. 2, TECHNOLOGY RD., V, SCIENCE-BASED INDUSTRIAL PARK,
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	7863759
CORRESPONDENCE DATA	
Fax Number:	(714)260-0748
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	7142600749
Email:	aghyeh@gmail.com
Correspondent Name:	CHIH FENG YEH
Address Line 1:	188 OLD CASTLE POINT RD.,
Address Line 4:	WAPPINGERS FALLS, NEW YORK 12590
ATTORNEY DOCKET NUMBER:	TF15IPC006
NAME OF SUBMITTER:	CHIH FENG YEH
SIGNATURE:	/Chih Feng YEH/
DATE SIGNED:	08/30/2015
Total Attachments: 2	
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ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) PACKAGE STRUCTURE AND METHOD FOR CHIP WITH TWO ARRAYS OF BONDING PADS ON BGA SUBSTRATE FOR PREVENTING GOLD BONDING WIRES FROM COLLAPSE

The PATENT RIGHTS referred to in this agreement are:

- (check one) a patent application for this invention, executed by the ASSIGNOR(S) concurrently with this assignment.
- U.S. patent application Ser. No. _____, filed _____ (MM.DD.YYYY)
- a U.S. patent application based on PCT International Application No. _____ filed on (date) _____ (U.S. patent application Ser. No. _____, if known)
- U.S. patent No. 7,863,759, issued Jan. 04, 2011

The PATENT RIGHTS assigned under this agreement are:

- (check one) U.S. patent rights only.
- Worldwide patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. or foreign patent application for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the undersigned whose signatures appear on page 2 of this Assignment.

(Name of Assignor) INTEGRATED CIRCUIT SOLUTION INC.
(Address) No.2, Technology Rd., V, Science-Based Industrial Park, Hsinchu 300, Taiwan, TAIWAN

- The ASSIGNOR is: (check one) An individual. A Partnership.
 A Corporation of TAIWAN (specify state or country)
 (other) _____

The ASSIGNEE referred to in this agreement is:

(Name of 1st Assignee) CHINGIS TECHNOLOGY CORPORATION
(Address) 3F, No.2, Technology Rd., V, Science-Based Industrial Park, Hsinchu 300, Taiwan

- The ASSIGNEE is: (check one) An individual. A Partnership.
 A Corporation of TAIWAN (specify state or country)
 (other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, hereby assign(s) the following rights to the ASSIGNEE, its successors and assigns:

- the full and exclusive right to the invention;
- the entire right, title and interest in and to the PATENT RIGHTS;
- the right to sue and recover for any past infringement; and
- the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE ASSIGNOR(S) TO
ASSIGNEE: CHINGIS TECHNOLOGY CORPORATION

INVENTION TITLE: PACKAGE STRUCTURE AND METHOD FOR CHIP
WITH TWO ARRAYS OF BONDING PADS ON BGA SUBSTRATE FOR
PREVENTING GOLD BONDING WIRES FROM COLLAPSE

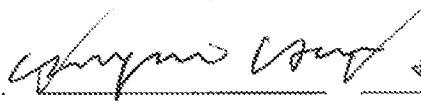
The ASSIGNOR(S) agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

The ASSIGNOR(S) hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment. In witness whereof, executed by the ASSIGNOR(S) on the date(s) following the ASSIGNOR(S) name(s).

Chang-Chaio Han

 8/18/2015

Name (of representative of solo or first Assignor, Please Print

Please Signature

Date

Print in order of: Given (First) Name FAMILY NAME, or FAMILY NAME, Given Name)

General Manager

Title (If Assignor, is a juristic entity)